

METHOD AND SYSTEM FOR INTEGRATED CIRCUIT PACKAGING

ABSTRACT OF THE DISCLOSURE

According to one embodiment of the invention, a system for packaging integrated circuits includes a mold tool for packaging integrated circuits. The mold tool includes a first mold plate that includes a first non-planar surface and a second mold plate that includes a second non-planar surface. The first and second non-planar surfaces form upper and lower surfaces of a mold cavity when the first and second mold plates are engaged. The mold tool also includes a distribution system coupled to the mold cavity. The distribution system transfers a mold compound into the mold cavity to substantially encapsulate an integrated circuit. The distribution system includes a gate runner coupled to the mold cavity. The gate runner funnels the mold compound into the mold cavity. The distribution system also includes a bridge insert that decreases wear on the gate runner as the mold compound is transferred through the gate runner.